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## PMP10856 REV B Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		PMP10856	Any	Printed Circuit Board	
2	C1, C2, C3	3	2.2uF	GRM32ER72A225KA35L	MuRata	CAP, CERM, 2.2 µF, 100 V, +/- 10%, X7R, 1210	1210
3	C4	1	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
	C5	1	220uF	EKZE350ETD221MJC5S	Nippon Chemi-Con	CAP, AL, 220 µF, 35 V, +/- 20%, 0.053 ohm, TH	TH, 2-Leads, Body 10x12.5mm, Pin Spacing 5mm
	C6, C8	2	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 μF, 50 V, +/- 10%, X7R, 1210	1210
	C7	1	330pF	GRM188R72E331KW07D	MuRata	CAP, CERM, 330 pF, 250 V, +/- 10%, X7R, 0603	0603
	C9	1	100pF	GRM1885C1H101JA01D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
	C11, C15	2	1uF	GRM21BR71H105KA12L	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0805	0805
9	C12	1	1000pF	VY2102M29Y5UG63V7	Vishay-Bccomponents	CAP, CERM, 1000pF, 300V, +/-20%, Y5U, Radial Disc 7.5mm, Is=7.5	Radial Disc 7.5mm, Is=7.5
10	C14	1	0.1uF	C0603C104J3RAC	Kemet	CAP, CERM, 0.1 µF, 25 V, +/- 5%, X7R, 0603	0603
11	C16, C18	2	470uF	UCD1H471MNQ1MS	Nichicon	CAP ALUM 470UF 50V 20% SMD	SMT Radial H13
12	C27	1	0.047uF	GRM188R71H473KA61D	MuRata	CAP, CERM, 0.047 µF, 50 V, +/- 10%, X7R, 0603	0603
13	C100	1	1000pF	GRM188R71E102KA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 10%, X7R, 0603	0603
14	D1	1	150V	PDS4150-13	Diodes Inc.	Diode, Schottky, 150 V, 4 A, PowerDI5	PowerDI5
	D2	1	24V	SMAJ24CA	Littelfuse	Diode, TVS, Bi, 24 V, 400 W, SMA	SMA
16	D3	1	200V	ES1D-13-F	Diodes Inc.	Diode, Ultrafast, 200 V, 1 A, SMA	SMA
17	D4	1	100V	GBU1001	Diodes Inc.	Diode, Switching-Bridge, 100 V, 10 A, TH	GBU
18	D10, D11	2	1.4V	BAS316,115	NXP Semiconductor	Diode, Ultrafast, 100V, 0.25A, SOD-323	SOD-323
19	F1	1		0452003.	Littelfuse	Fuse, 3A, 125V, SMD	SloBlo452
20	J2	1		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm
21	L6	1	50 ohm	HI1206T500R-10	Laird-Signal Integrity Products	Ferrite Bead, 50 ohm @ 100MHz, 6A, 1206	1206
22	Q1	1	100V	CSD19534Q5A	Texas Instruments	MOSFET, N-CH, 100 V, 10 A, SON 5x6mm	SON 5x6mm
23	R1	1	499k	CRCW0603499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.1 W, 0603	0603
24	R2	1	10	CRCW120610R0JNEA	Vishay-Dale	RES, 10, 5%, 0.25 W, 1206	1206
25	R3, R13	2	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
26	R4	1	100	CRCW1206100RJNEA	Vishay-Dale	RES, 100, 5%, 0.25 W, 1206	1206
	R5	1	37.4k	CRCW060337K4FKEA	Vishay-Dale	RES, 37.4 k, 1%, 0.1 W, 0603	0603
28	R6, R15	2	1.00k	CRCW06031K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.1 W, 0603	0603
29	R7	1	130k	CRCW0603130KFKEA	Vishay-Dale	RES, 130 k, 1%, 0.1 W, 0603	0603
30	R8	1	0.1	CRA2512-FZ-R100ELF	Bourns	RES, 0.1, 1%, 3 W, 2512	2512
31	R9	1	1.00k	CRCW08051K00FKEA	Vishay-Dale	RES, 1.00 k, 1%, 0.125 W, 0805	0805
32	R14	1	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
33	R28	1	100k	CRCW0603100KFKEA	Vishay-Dale	RES, 100 k, 1%, 0.1 W, 0603	0603
34	R29	1	1.15k	CRCW06031K15FKEA	Vishay-Dale	RES, 1.15 k, 1%, 0.1 W, 0603	0603
35	T1	1	60 uH	750315252	Wurth Elektronik eiSos	Transformer, 60 uH, TH	21.08x21.08mm
36	TP3	1	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
37	TP4	1	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
38	TP5, TP6	2	White	5012	Keystone	Test Point, Multipurpose, White, TH	White Multipurpose Testpoint
39	U1	1		LM5022MM	Texas Instruments	60V Low Side Controller for Boost and SEPIC, 10-pin MSOP	MUB10A
40	U2	1		TL431AIDBZT	Texas Instruments	Adjustable Precision Shunt Regulator, 34 ppm / degC, 100 mA, -40 to 85 degC, 3-pin SOT-23 (DBZ), Green (RoHS & no Sb/Br)	DBZ0003A
41	U6	1		VOS617A-7X001T	Vishay-Semiconductor	OptoCoupler, Phototransitor, 80-160%, SSOP-4	7x2.12x2.6mm

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